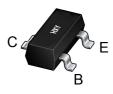


FEATURES

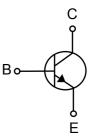
- Collector Current: I_C=0.2A
- Power Dissipation of 200mw





Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MMBT3904	SOT-23	1AM	3000



MAXIMUM RATINGS (Ta=25 unless otherwise noted)

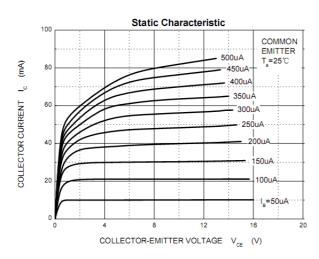
Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CBO}	60	V
Collector-Emitter Voltage	V _{CEO}	40	V
Emitter-Base Voltage	V _{EBO}	6	V
Collector Current	Ι _c	200	mA
Collector Power Dissipation	Pc	200	mW
Thermal Resistance From Junction To Ambient	R _{OJA}	625	°C/W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55~+150	°C

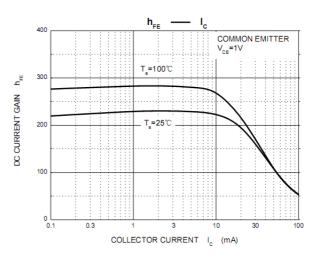


ELECTRICAL CHARACTERISTIC						
Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Collector-base breakdown voltage	V _{(BR)CBO}	I _C =10μΑ, I _E =0	60			V
Collector-emitter breakdown voltage	V _{(BR)CEO}	I _C =1mA, I _B =0	40			V
Emitter-base breakdown voltage	V _{(BR)EBO}	I _E =10μA, I _C =0	6			V
Collector cut-off current	I _{CEX}	V _{CE} =30V, V _{EB(off)} =3V			50	nA
Collector cut-off current	I _{CBO}	V _{CB} = 60V, I _E =0			100	nA
Emitter cut-off current	I _{EBO}	V _{EB} =5V, I _C =0			100	nA
	h _{FE(1)}	V _{CE} =1V, I _C =10mA	100		300	
DC current gain	h _{FE(2)}	V _{CE} =1V, I _C =50mA	60			
	h _{FE(3)}	V _{CE} =1V, I _C =100mA	30			
Collector-emitter saturation voltage	V _{CE(sat)}	I _C =50mA, I _B =5mA			0.3	V
Base-emitter saturation voltage	V _{BE(sat)}	I _C =50mA, I _B =5mA			0.95	V
Transition frequency	f⊤	V _{CE} =20V,I _C =10mA, f=100MHz	300			MHz
Delay time	t _d	V_{CC} =3V, $V_{BE(off)}$ =-0.5V I _C =10mA,	:		35	ns
Delay time		I _{B1} =1mA			35	
Rise time	tr	V_{CC} =3V, $V_{BE(off)}$ =-0.5V I _C =10mA,			35	ns
		I _{B1} =1mA				
Storage time	ts	V_{CC} =3V, I _C =10mA, I _{B1} = I _{B2} =1mA			200	ns
Fall time	t _f	V_{CC} =3V, I_{C} =10mA, I_{B1} = I_{B2} =1mA			50	ns

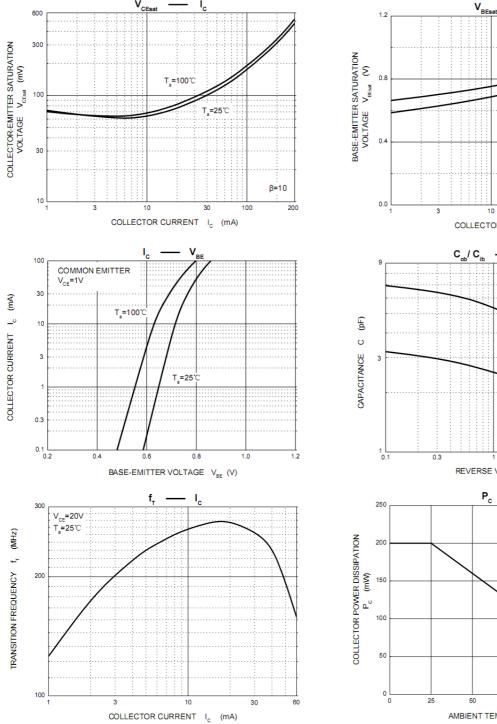
ELECTRICAL CHARACTERISTICS (Ta=25 unless otherwise specified)

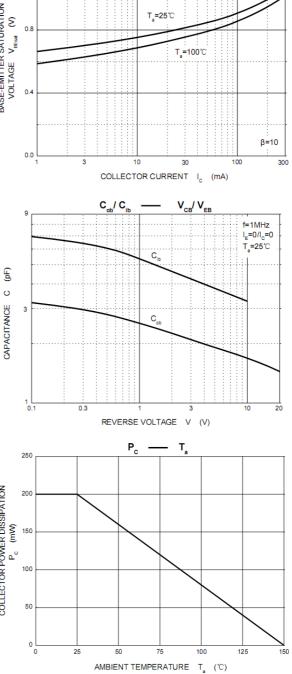
Typical Characteristics





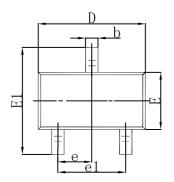


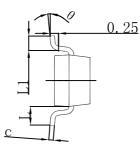


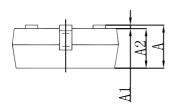




SOT-23 Package Outline Dimensions

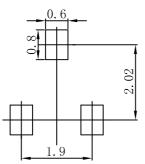






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
e	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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